

BRLV10100RA

Rev. B May.-2018

TO-220

O03 Tm.06ttky D 79.8T

/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Recurrent Peak Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} , V_{RWM} V_{DC}	100	V
RMS Reverse Voltage	V_{RMS}	70	V
Average forward rectified current	$I_{F(AV)}$	10	A
Non Repetitive Peak Surge Current	I_{FSM}	80	A
Thermal Resistance Junction to Case	R_{JC}	2.8	/W
Junction and Storage Temperature Range	T_j T_{stg}	-40 +150	

/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Breakdown Reverse Voltage	V_{BR}	$I_R=100\mu A(Ta=25)$	100			V
Forward Voltage	V_F	$I_F=1A(Ta=25)$		0.41	0.48	V
		$I_F=3A(Ta=25)$		0.48	0.53	V
		$I_F=1A(Ta=125)$			0.44	V
		$I_F=3A(Ta=125)$			0.50	V
Instantaneous Reverse Current	I_R Note 1	$V_R=100V(Ta=25)$		10	50	A
		$V_R=100V(Ta=125)$			10	mA

/Notes

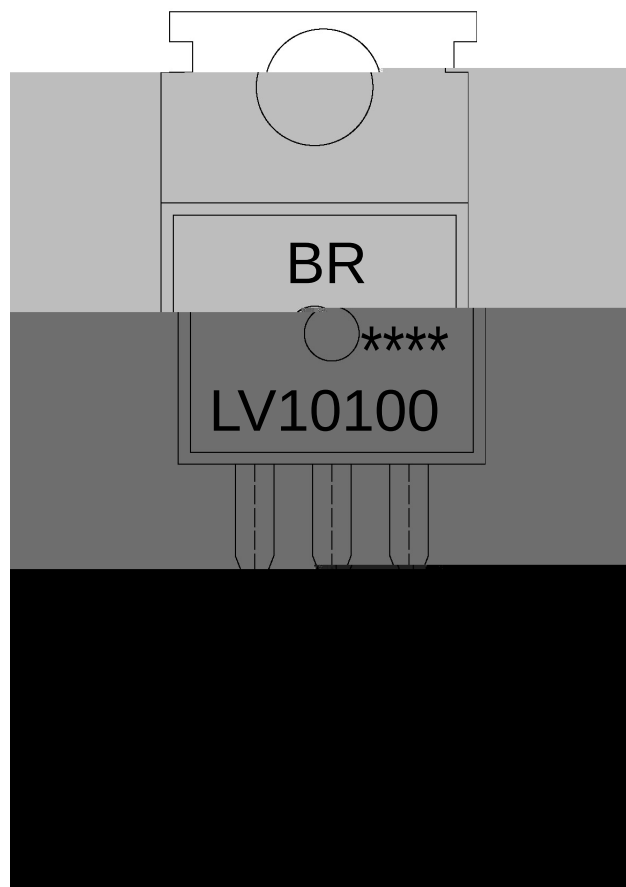
1. /Short duration pulse test used to minimize self-heating effect.
2. / Unless otherwise noted, values for the parameters of a single chip

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DATA SHEET

/ Marking Instructions



BR

LV10100

Note:

BR:

Company Code

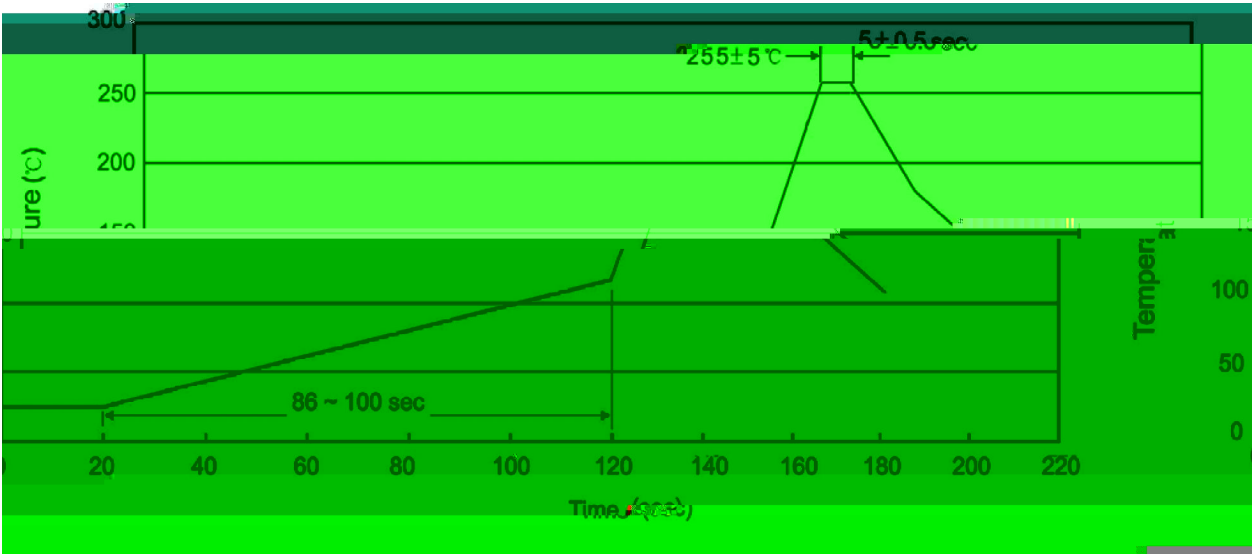
LV10100

Product Type.

****:

Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- 1

25 150

60 90sec;
- 2

255±5

5±0.5sec;
- 3

2 10

/sec.
- 1.Preheating:25~150

, Time:60~90sec.
- 2.Peak Temp.:255±5

, Duration:5±0.5sec.
3. Cooling Speed: 2~10

/sec.

/ Resistance to Soldering Heat Test Conditions

270±5 10±1 sec. Temp.:270±5 Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type	Units		Dimension	(unit mm ³)
	Units/Bag	Bags/Inner Box		
	/	/		